

January 26, 2018

PCN

RF360 SAW components in ceramic SMD packages for automotive electronics

As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace the 4-inch wafer material used in the front-end production processes for SMD components with pyrolytic silicon nitride passivation (PSN), LT-Zer0-TCF (LT) and HQTCF (LN) for automotive electronics.

Affected products

Ordering code	Ordering code	Ordering code
B39162B3400U410	B39162B3431B710	B39162B3517U510
B39162B3401B710	B39921B3432U410	B39162B3519U410
B39232B3404U410	B39931B3433U410	B39162B3524B710
B39162B3405H910	B39871B3440U410	B39162B3525U510
B39162B3412U410	B39871B3441U410	B39232B3526U510
B39162B3413U410	B39232B3442U410	B39162B3528U510
B39162B3414U510	B39871B3443U410	B39232B3595U410
B39162B3415U410	B39761B3444Z810	B39122B3596U410
B39232B3416U410	B39761B3445U410	B39242B3912U410
B39162B3417U410	B39931B3446U410	B39162B3913U410
B39871B3418U410	B39232B3447U410	B39931B3916U410
B39921B3419U410	B39871B3448U510	B39242B3918U410
B39871B3420U410	B39162B3451U410	B39232B3920U510
B39152B3421U410	B39162B3470H910	B39931B3921U410
B39162B3423U410	B39232B3471H910	B39162B3923U410
B39162B3424U410	B39921B3474H910	B39931B3926U410
B39232B3425U510	B39731B3476H910	B39232B3927U510
B39132B3428U410	B39731B3477B510	B39761B3929U410
B39911B3429U410	B39162B3478H910	
B39871B3430U410	B39731B3479B510	

January 26, 2018

The announced changes will be effective for both released and newly designed components. There will be no impact on product quality, specification or delivery performance. The components will be qualified according to AEC-Q200 based on reference types.

For components with 4-inch wafer material:

Deadline for last orders: December 31, 2018

Last shipments by: April 30, 2019

Enclosure PCN (ID No. M311)

Contact Michael Loeffler, RF360 D AE PM, Munich

Customers are asked to address inquiries directly to their sales contacts.

Product / Process Change Notification

1. ID No.: M311		2. Date of announcement: Januar 26, 2018
3. Product / product group: SAW AE SMD components with PSN passivation, LT-Zer0-TCF and HQTCF		
Old ordering code: SAW AE SMD components with PSN passivation, LT-Zer0 TCF and HQTCF: B39162B3400U410 B39162B3401B710 B39232B3404U410 B39162B3405H910 N: B39162B3412U410 B39162B3413U410 N: B39162B3414U510 N: B39162B3415U410 N: B39232B3416U410 N: B39162B3417U410 N: B39871B3418U410 N: B39921B3419U410 N: B39871B3420U410 B39152B3421U410 B39162B3423U410 B39162B3424U410 B39232B3425U510 B39132B3428U410 B39911B3429U410 B39871B3430U410 N: B39162B3431B710 N: B39931B3433U410 B39921B3432U410 B39871B3440U410 B39871B3441U410 B39232B3442U410 B39871B3443U410 B39761B3444Z810 B39761B3445U410 B39931B3446U410 B39232B3447U410 B39871B3448U510 N: B39162B3451U410 B39162B3470H910 B39232B3471H910 B39921B3474H910	New ordering code: no change	Customer part number:

<p>N: B39731B3476H910 N: B39731B3477B510 N: B39162B3478H910 B39731B3479B510 B39162B3517U510 B39162B3519U410 B39162B3524B710 B39162B3525U510 B39232B3526U510 B39162B3528U510 B39232B3595U410 B39122B3596U410 B39242B3912U410 B39162B3913U410 B39931B3916U410 B39242B3918U410 B39232B3920U510 B39931B3921U410 B39162B3923U410 B39931B3926U410 B39232B3927U510 B39761B3929U410</p>		
<p>4. Description of change: RF360 SAW AE SMD components with PSN passivation, LT-Zer0-TCF and HQTCF: As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace the 4-inch wafer material used in the front-end production processes for SMD components with pyrolytic silicon nitride passivation (PSN), LT-Zer0-TCF (LT) and HQTCF (LN) for automotive electronics. (Update of PCN M306 - part 2 - with additional part numbers - marked with "N:" above).</p>		
<p>5. Effect on the product or for the customer (benefit / quality, specification, lead time): The changes have no effect on product quality, specifications, ordering codes or delivery performance. There is no change of packages or packing.</p>		
<p>6. Quality assurance measures / risk assessment: All types that change wafer size will be re-qualified according to AEC Q200 (by representative types) prior to sampling and volume production.</p>		
<p>7. Scheduled date of change: Deadline for last orders of components with current wafer size (LTB): December 31, 2018 Deadline for last shipments (LTS): April 30, 2019 Please note that all customers holding PPAPs and other qualification documents (mainly automotive customers) will be addressed separately by RF360 Sales.</p>		
<p>8. Estimated date of first delivery of changed product: January 1, 2019</p>		

RF360

If RF360 does not receive notification to the contrary within a period of 10 weeks, RF360 assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped

Quality Management

Name Franz Schoenegger

Signature

signed: Schoenegger

Product Marketing

Name Michael Loeffler

Tel. +49 89 20805 3403

E-Mail michael.loeffler@rf360jv.com

Signature

signed: Michael Loeffler

Customer feedback

Customer acknowledgement

Signature